

Introducing

Sockets and Hardware for LGA 1156 Processors

TE Connectivity's surface mount LGA socket was designed for use with Intel's® Core™ i7 LGA 1156 processor. The contacts have solder balls for surface mount onto the PCB, while the top side provides a cantilever beam interface to the package. The integrated lever mechanism (ILM) generates the Z-axis compression load. A robust bolster plate eliminates PCB bowing during compression. The sockets have been validated to Intel Design Guides.





KEY FEATURES

- 1156 contacts with a 0.914mm x 0.914mm grid.
- Available with 15 Gold or Gold flash contact plating.
- Socket housing facilitates efficient soldering to the PCB board.
- Socket is supplied with a cap to facilitate vacuum pick and place.
- · Backplates are available in zinc or nickel plating.
- ILM, screws and backplate must be ordered separately. Kits are also available for ease in ordering.
- Each ILM assembly requires two ILM screws and one ILM shoulder screw.

Tyco Electronics Corporation Technical Support Center

Internet: www.tycoelectronics.com/help

USA: +1 (800) 522-6752 Canada: +1 (905) 470-4425

Central America

+52 (0) 55-1106-0814 +55 (0) 11-2103-6000 South America: Germany: +49 (0) 6251-133-1999 UK: +44 (0) 8706-080208 France: +33 (0) 1-3420-8686 Netherlands: +31 (0) 73-6246-999 +86 (0) 400-820-6015 China:

www.tycoelectronics.com

© 2011 Tyco Electronics Corporation. All Rights Reserved

3-1773455-8 CIS-MS-05/2011

TE Connectivity, TE connectivity (logo) and TE (logo) are trademarks. Other logos, product and/or company names might be trademarks of their respective owners. Other products, logos, and company names mentioned herein may be

trademarks of their respective owners

APPLICATIONS

- · Desktop computers
- · Low end servers

ELECTRICAL

- · Low level bulk contact resistance: 22 milliohms max avg.
- Insulation resistance: 800 milliohms min. @ 500 VDC

MECHANICAL

· Nominal Deflection: .45 mm

· Durability: 30 cycles

· Package mating and unmating operation force of lever: 49N (5kgf) maximum

MATERIALS

Socket assembly

Contact: Copper Alloy, gold plating at contact area on nickel under plating.

Base housing: High temperature thermoplastic UL94V-0

Cap: High temperature thermoplastic UL94V-0 · ILM load plate and lever: Stainless steel

· ILM frame, ILM screw and shoulder screw: Steel

· ILM Insulator: Polycarbonate

· Backplate assembly: Steel, zinc or nickel plated

· Backplate Insulator: Polycarbonate

APPLICATIONS AND SPECIFICATION

· Application specification 114-5444

• Instruction sheet 411-78321

• Product Spec 108-78586

PRODUCT OFFERINGS

Part Number	Description	Plating	
2040540-1	LGA 1156 Socket	15 Gold	
2040540-2	LGA 1156 Socket	Gold Flash	
2013882-1	ILM Assembly		
2013882-2	ILM Assembly with ILM screws		
2013883-1	Back plate assembly	Zinc	
2013883-2	Back plate assembly	Nickel	
2013884-1	Shoulder Screw		
2040979-1	ILM Screw		

ILM/Back Plate Kits

Part No.	2013882-1 ILM Assembly	2013884-1 Shoulder Screw	2040979-1 ILM Screw	2013883-1 Back Plate Assembly - Zinc Plated	2013883-2 Back Plate Assembly - Ni Plated	
2069838-1	1	1	2	1	0	
2069838-3	0	1	2	1	0	Qty
2069838-4	1	1	2	0	1	per kit
2069838-5	0	1	2	0	1	



While TE has made every reasonable effort to ensure the accuracy of the information in this brochure, TE does not guarantee that it is error-free, nor does TE make any other representation, warranty or guarantee that the information is accurate, correct, reliable or current. TE reserves the right to make any adjustments to the information contained herein at any time without notice. TE expressly disclaims all implied warranties regarding the information contained herein, including, but not limited to, any implied warranties of merchantability or fitness for a particular purpose. The dimensions in this catalog are for reference purposes only and are subject to change without notice. Specifications are subject to change without notice. Consult TE for the latest dimensions and design specifications.